Method for Manufacturing Semiconductor Device and Heat-Resistant Pressure-Sensitive Adhesive Tape for Use Therein

ABSTRACT

A method for manufacturing a semiconductor device of the present invention, comprises the steps of mounting and bonding semiconductor chips onto die pads of a metal lead frame having an outer pad side to which a heat-resistant pressure-sensitive adhesive tape is attached; wiring a bonding wire between each termination of the lead frame and each electrode pad on the semiconductor chips sealing semiconductor chips in a sealing resin from one side; and cutting the sealed body into individual semiconductor devices.

In this invention, the heat-resistant pressure-sensitive adhesive tape comprises a base layer made of a polyimide resin and a pressure-sensitive adhesive layer with a thickness of 1 to 20 μm that is made of an acrylic resin and has a storage elastic modulus of at least 1.0×10^5 Pa at 200°C.



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FIG. 1



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